

# THOMSON SEMICONDUCTORS

## TL 1003 → TL 8003 THYRISTORS T-25-11

General purpose SCR suited for power supplies up to 400 Hz on resistive or inductive loads.

- $V_{DRM} = V_{RRM}$  up to 800 V.
- Glass passivated chip - High stability and reliability.
- High surge capability.

*Thyristors à usage général pour des alimentations jusqu'à 400 Hz sur charges résistives ou inductives.*

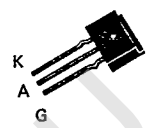
- $V_{DRM} = V_{RRM}$  jusqu'à 800 V.
- Pastille glassivée - Grande stabilité des caractéristiques.
- Courant de surcharge élevé.

$$I_T(RMS) = 1,6 A / T_L = 50^\circ C$$

$$V_{DRM} = V_{RRM}$$

$$100 V < = < 800 V$$

Case : TL (CB-274) plastic  
Boîtier :



ABSOLUTE RATINGS (LIMITING VALUES) VALEURS LIMITEES ABSOLUES D'UTILISATION	Symbol	Value	Unit
RMS on-state current* <i>Courant efficace à l'état passant*</i>	$I_T(RMS)$	1,6 @ $T_L = 50^\circ C$	A
Mean on-state current* <i>Courant moyen à l'état passant*</i>	$I_T(AV)$	1 @ $T_L = 50^\circ C$	A
Non repetitive surge peak on-state current** <i>Courant non répétitif de surcharge crête accidentelle à l'état passant**</i>	$I_{TSM}$ $I_{TSM}$	73 (t = 8,3 ms) 70 (t = 10 ms) @ $T_j \leq 110^\circ C$	A A
$I^2t$ for fusing <i>Valeur de la constante <math>I^2t</math></i>	$I^2t$	25 (t = 10 ms) @ $T_j \leq 110^\circ C$	A <sup>2</sup> s
Critical rate of rise of on-state current*** <i>Vitesse critique de croissance du courant à l'état passant***</i>	di/dt	100	A/ $\mu$ s
Storage and operating junction temperatures <i>Températures extrêmes de stockage et de jonction en fonctionnement</i>	$T_{stg}$ $T_j$	- 40, + 150 - 40, + 110	$^\circ C$ $^\circ C$

@ $T_j = 110^\circ C$	TL 1003	TL 2003	TL 4003	TL 6003	TL 8003
$V_{DRM} = V_{RRM}$ (V)	100	200	400	600	800

Thermal resistances <i>Résistances thermiques</i>	Symbol	Value	Unit
- Junction-leads <i>Jonction-connexions</i>	$R_{th(j-l)}$	35	$^\circ C/W$
- Junction-ambient on printed circuit (with Cu 1 cm <sup>2</sup> ) <i>Jonction-ambiante sur circuit imprimé (avec Cu 1 cm<sup>2</sup>)</i>	$R_{th(j-a)}$	50	$^\circ C/W$

\*Single phase circuit, 180° conduction angle  
\*Circuit monophasé, angle de conduction 180°  
\*\*\* $I_{GT} = 100$  mA    di/dt = 1 A/ $\mu$ s

\*\*Half-sine wave  
\*\*Demi-onde sinusoïdale

May 1984 - 1/4

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T.25-11

**GATE CHARACTERISTICS (Maximum values)**  
**CARACTERISTIQUES DE GACHETTE (Valeurs maximales)**

PGM = 20 W (t = 10 μs)  
 PG(AV) = 0,1 W

IFGM = 1 A (t = 10 μs)  
 VFGM = 15 V (t = 10 μs)

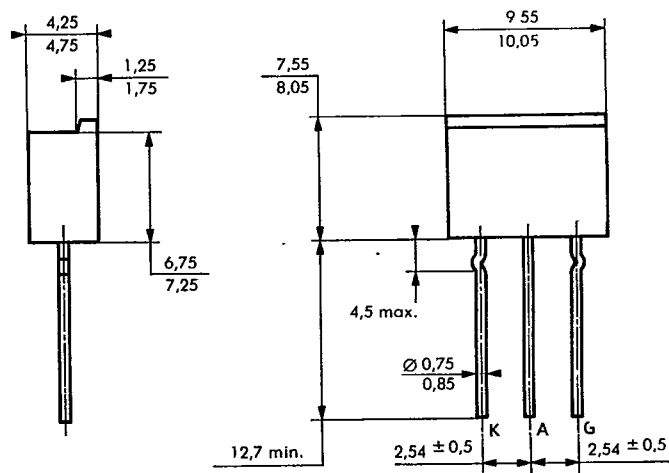
VRGM = 5 V

**ELECTRICAL CHARACTERISTICS**  
**CARACTERISTIQUES ELECTRIQUES**

Symbol	Value			Unit	Test conditions			
	min	typ	max					
I <sub>GT</sub>			15	mA	T <sub>j</sub> = 25°C	V <sub>D</sub> = 12 V	R <sub>L</sub> = 33 Ω	t <sub>p</sub> ≥ 20 μs
V <sub>GT</sub>		1,2	3	V	T <sub>j</sub> = 25°C	V <sub>D</sub> = 12 V	R <sub>L</sub> = 33 Ω	t <sub>p</sub> ≥ 20 μs
V <sub>GD</sub>	0,2			V	T <sub>j</sub> = 110°C	V <sub>D</sub> = V <sub>DRM</sub>	R <sub>L</sub> = 3,3 kΩ	
I <sub>H</sub>		20		mA	T <sub>j</sub> = 25°C	I <sub>T</sub> = 100 mA	Gate open	
V <sub>TM</sub>			1,8	V	T <sub>j</sub> = 25°C	I <sub>TM</sub> = 3,2 A	t <sub>p</sub> = 10 ms	
I <sub>DRM</sub>			2	mA	T <sub>j</sub> = 110°C	V <sub>DRM</sub> specified		
I <sub>RRM'</sub>			2	mA	T <sub>j</sub> = 110°C	V <sub>RRM</sub> specified		
t <sub>gt</sub>		1,5		μs	T <sub>j</sub> = 25°C I <sub>G</sub> = 100 mA	I <sub>T</sub> = 3,2 A di <sub>G</sub> /dt = 1 A/μs	V <sub>D</sub> = V <sub>DRM</sub>	
t <sub>q</sub>		80		μs	T <sub>j</sub> = 110°C di <sub>R</sub> /dt = 10 A/μs	I <sub>T</sub> = 1 A dv/dt = 20 V/μs	V <sub>R</sub> = 10 V	V <sub>D</sub> = 0,67 V <sub>DRM</sub> Gate open
dv/dt*		100		V/μs	T <sub>j</sub> = 110°C	Linear slope up to 0,67 V <sub>DRM</sub> specified Gate open		

\*For higher guaranteed values, please consult us.

**CASE DESCRIPTION**  
**DESCRIPTION DU BOITIER**



Cooling method : by convection (method A)  
 Marking : type number  
 Weight : 0,8 g

TL (CB-274) plastic

T.25-11

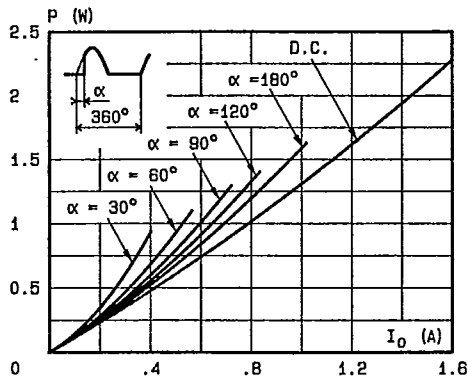


Fig. 1 - Maximum mean power dissipation - versus mean on-state current.

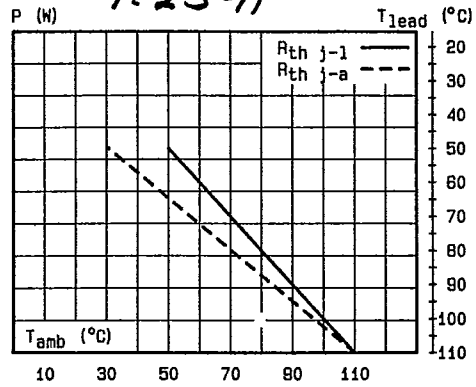


Fig. 2 - Correlation between maximum mean power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{lead}$ ).

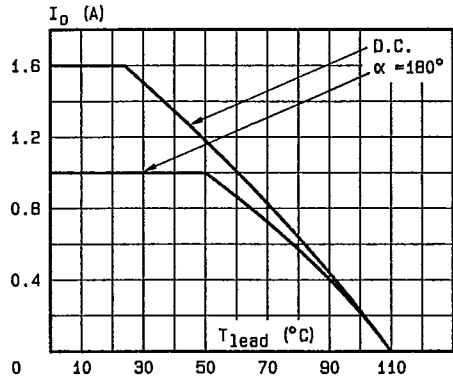


Fig. 3 - Mean on-state current versus leads temperature.

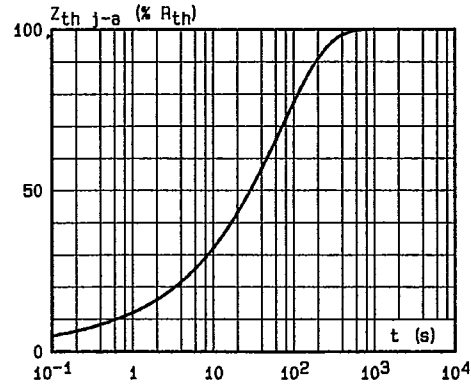


Fig. 4 - Thermal transient impedance to ambient versus pulse duration.

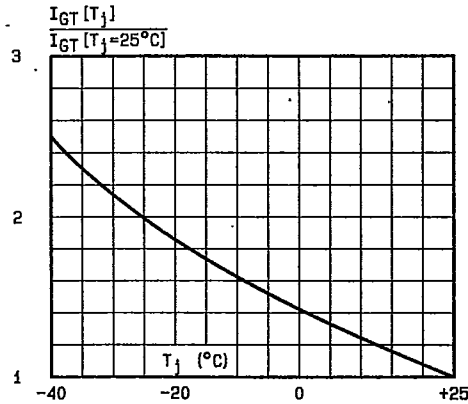


Fig. 5 - Relative variation of gate trigger current versus junction temperature.

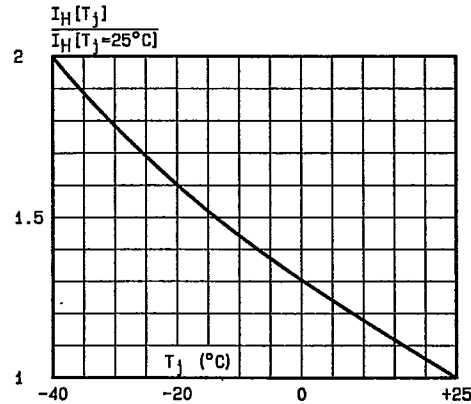


Fig. 6 - Relative variation of holding current versus junction temperature.

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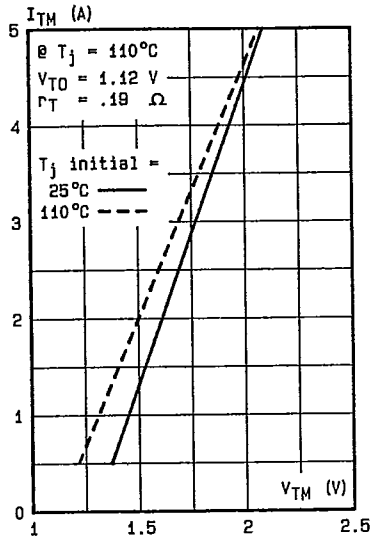


Fig.7 - On-state characteristics at low level (maximum values).

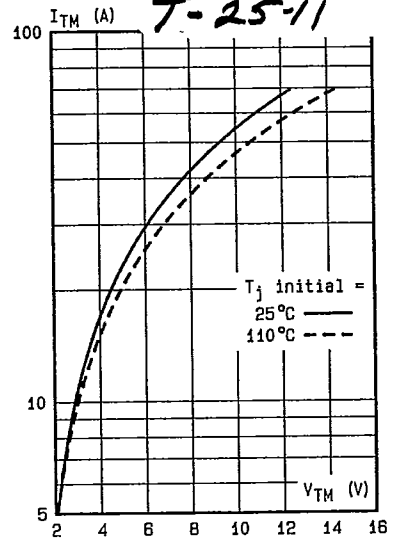


Fig.8 - On-state characteristics at high level (maximum values).

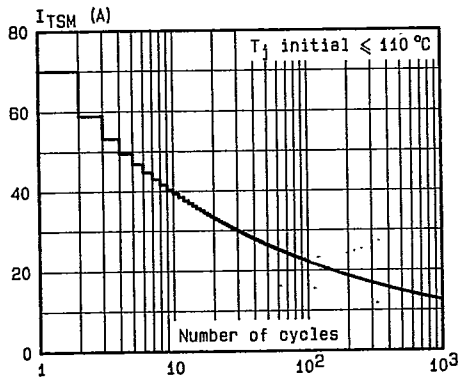


Fig.9 - Non repetitive surge peak on-state current versus number of cycles.

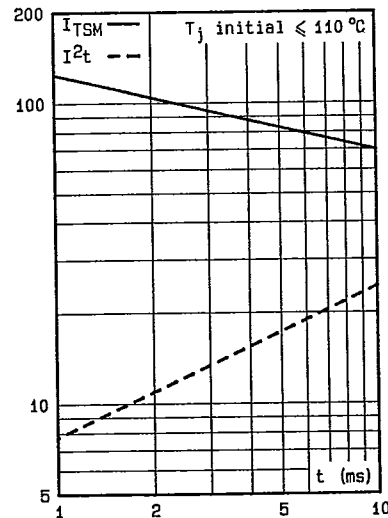


Fig.10 - Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \leq 10$  ms, and corresponding value of  $I^2t$ .